



Product Change Notification - KSRA-24HJEE206

Date:

30 Jun 2020

Product Category:

Simple and Complex Programmable Logic

Affected CPNs:**Notification subject:**

CCB 4254 Initial Notice: Qualification of GTK as a new assembly site for selected Atmel products available in 24L SPDIP (.300in) package.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of GTK as a new assembly site for selected Atmel products available in 24L SPDIP (.300in) package.

Pre Change:

Assembled at LPI using CRM-1033BF die attach, and G600 molding compound material

Post Change:

Assembled at LPI using EN-4900GC die attach, and G631M molding compound material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Lingsen Precision Industries, LTD. (LPI)	Greatek Electronic Inc. (GTK)
Wire material	Au	Au
Die attach material	CRM-1033BF	EN-4900GC
Molding compound material	G600	G631M
Lead frame material	A194	A194
Packing Media: Tube	Tube Color	Clear
	Plug Color	Green/White
	Tube Dimensions	Minor dimensional changes. See pre and post change comparison

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTK as a new assembly site

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

November 2020



Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	June 2020					-->	November 2020				
Workweek	23	24	25	26	27		45	46	47	48	49
Initial PCN Issue Date				X							
Qual Report Availability											X
Final PCN Issue Date											X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

June 30, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-24HJEE206_Packing Pre and Post Change.pdf](#)

[PCN_KSRA-24HJEE206_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATF750C-7PX

ATF750LVC-15PU

ATF750CL-15PU

ATF750C-10PU

ATF22V10C-7PX

ATF22V10C-10PU

ATF22LV10C-10PU

ATF22V10C-15PU

ATF22V10CQZ-20PU

ATF22LV10CQZ-30PU

CCB 4254
Pre and Post Change Summary
PCN#: KSRA-24HJEE206



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Packing Information (Tube Comparison)

PRE-CHANGE (LPI)



Package	Lead Count	Body Size	Units/Tube	Length (inch)	End Plugs
SPDIP	24	300 mils	15	20.00+/- 0.030	Green/White

POST-CHANGE (GTK)



Package	Lead Count	Body Size	Units/Tube	Length (inch)	End Plugs
SPDIP	24	300 mils	15	24.00+/- 0.025	Blue/White



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QUALIFICATION PLAN SUMMARY

PCN# KSRA-24HJEE206

**Date:
May 28, 2020**

**Qualification of GTK as a new assembly site for selected
Atmel products available in 24L SPDIP (.300in) package.**

Purpose: Qualification of GTK as a new assembly site for selected Atmel products available in 24L SPDIP (.300in) package.

Misc.	Assembly site	GTK
	MP Code (MPC)	197117JDBC02
	Part Number (CPN)	ATF750CL-15PU
	MSL information	NA
	Assembly Shipping Media (T/R, Tube/Tray)	Tube (GTK 41-01002-001)
	Base Quantity Multiple (BQM)	15
	Reliability Site	MPHIL
	CCB No	4254
Lead-Frame	Paddle size	160 x160
	Material	A194
	DAP Surface Prep	Spot Plating
	Treatment	None
	Process	Stamped
	Lead-lock	Yes
	Part Number	11-0124K-002
	Lead Plating	Matte Sn
	Strip Size (mm)	10X1
	Strip Density	10 ea/strip
Bond Wire	Material	Au
Die Attach	Part Number	EN-4900GC
	Conductive	Yes
MC	Part Number	G631M
PKG	PKG Type	SPDIP
	Pin/Ball Count	24
	PKG width/size	300 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	ATE Test Site	REL Test Site	Special Instructions
Standard Pb-free Solderability	J-STD-002D ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing. Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5	MPHIL	MPHIL	Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	MPHIL	MPHIL	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5	MPHIL	MPHIL	30 bonds from a min. 5 devices.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30		5	MPHIL	MPHIL	
Lead Integrity	JESD22 B105	5	0	1	5	0 (No lead breakage or cracks)	5	MPHIL	MPHIL	10 leads from each of 5 parts. Not required for SMD, only required for through-hole.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MPHIL	MPHIL	
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C.	231	15	3	738	0	15	MPHIL	MPHIL	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MPHIL	MPHIL	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	+130°C/85% RH for 96 hrs Electrical test pre and post stress at +25°C	77	5	3	246	0	10	MPHIL	MPHIL	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at room temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	MPHIL	MPHIL	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.